

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT7004275

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ELAD MENTOVICH	11/01/2021
ANNA SANDOMIRSKY	11/01/2021
DIMITRIOS KALAVROUZOTIS	11/01/2021
RECEIVING PARTY DATA	
Name:	MELLANOX TECHNOLOGIES, LTD.
Street Address:	P.O. BOX 586
City:	YOKNEAM
State/Country:	ISRAEL
Postal Code:	20692
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17517693
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Correspondent Name:	KLIGLER & ASSOCIATES PATENT ATTORNEYS LTD.
Address Line 1:	P. O. BOX 57651
Address Line 4:	TEL AVIV, ISRAEL 61576
ATTORNEY DOCKET NUMBER:	1058-1269.1
NAME OF SUBMITTER:	SVETLANA RUDNIK
SIGNATURE:	/Svetlana Rudnik/
DATE SIGNED:	11/03/2021
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 6	
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DECLARATION AND ASSIGNMENT

AS A BELOW NAMED INVENTOR, I hereby declare that:

This declaration and assignment are directed to the attached patent application, entitled HEAT REMOVAL FROM SILICON PHOTONICS CHIP USING A RECESSED SIDE-BY-SIDE THERMAL DISSIPATION LAYOUT (hereinafter, the Application).

The above-identified Application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the Application.

I hereby acknowledge that any willful false statement made in the above declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the sum of one dollar (\$1.00) and other good and valuable consideration paid to me, the receipt and sufficiency of which are hereby acknowledged, I agree to assign, and hereby do assign, to:

MELLANOX TECHNOLOGIES, LTD., an Israeli company, having a place of business at P.O. Box 586, Yokneam 20692, Israel (hereinafter, Assignee),

my entire right, title and interest in and to any and all inventions described and/or claimed in the Application (hereinafter, the Invention), including, without limitation, the above-mentioned Application itself and all other provisional and non-provisional applications deriving from the above-mentioned Application, and including any original and/or reissued Letters Patent of the United States granted for the Invention and any divisions, reissues, continuations, continuations-in-part, and extensions of any such patent application(s), and including any patents or other forms of protection of industrial property that may be granted in relation to the Invention in any other country, and including the rights to file and prosecute all applications for patents and other forms of protection of industrial property in the United States and other countries and to claim priority from the above-mentioned Application in the United States and in any other country, and including the subject matter of any and all claims which may be obtained in such patents and the right to enforce such patents.

I hereby authorize and request the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from the above-mentioned Application and any divisions, reissues, continuations, or continuations-in-part thereof to the Assignee, as Assignee of the entire interest, and likewise authorize officials of other countries to issue patents and other forms of industrial property protection to the Assignee.

I hereby covenant that I have full right to convey the entire interest herein assigned, and that I have not executed and will not execute any agreement in conflict herewith.

I agree to execute all papers in connection with the above-mentioned Application and any applications filed as divisions, reissues, continuations, or continuations-in-part

thereof or otherwise deriving from the above-mentioned Application, including separate assignments in connection with such applications, that the Assignee may deem desirable for the purposes of obtaining, protecting and enforcing its rights in the Invention.

I agree to communicate to the Assignee or representatives thereof any facts known to me respecting the Invention and improvements thereof, and will, upon request, but without expense to myself, testify in any legal proceedings regarding the invention and provide any other assistance deemed necessary by the Assignee to obtain, protect and enforce its rights in the Invention.

This Assignment shall be binding upon the heirs, executors, administrators, and assigns of each of the Inventors listed below, and shall inure to the benefit of the heirs, executors, administrators, successors and assigns of the Assignee.

IN WITNESS WHEREOF, the Inventors have executed this Assignment on the date or dates indicated below:

First inventor: Elad Mentovich, citizen of Israel

Inventor signature: /ELAD MENTOVICH/ Date: 11/01/2021

Residence: 13 Moshe Perlok Street, Tel Aviv, Israel

Second inventor: Anna Sandomirsky, citizen of Israel

Inventor signature: _____ Date: _____

Residence: 4/11 Havatzelet Street, Nesher, Israel

Third inventor: Dimitrios Kalavrouziotis, citizen of Greece

Inventor signature: _____ Date: _____

Residence: Efesou 12, Papagou 15669, Greece

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Inventor signature: _____ Date: _____

Residence: 13 Moshe Perlok Street, Tel Aviv, Israel

Second inventor: Anna Sandomirsky, citizen of Israel

Inventor signature: /Anna Sandomirsky/ Date: 01-nov-2021

Residence: 4/11 Havatzelet Street, Nesher, Israel

Third inventor: Dimitrios Kalavrouziotis, citizen of Greece

Inventor signature: _____ Date: _____

Residence: Efesou 12, Papagou 15669, Greece

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Second inventor: Anna Sandomirsky, citizen of Israel

Inventor signature: _____ Date: _____

Residence: 4/11 Havatzelet Street, Nesher, Israel

Third inventor: Dimitrios Kalavrouziotis, citizen of Greece

Inventor signature: /DIMITRIOS KALAVROUZOTIS/ Date: 1 Nov 2021

Residence: Efesou 12, Papagou 15669, Greece